

High-Reliability

Precision Die-Attach (PDA) Preforms

- Highly accurate thickness control
- Precision edge quality, virtually burr-free
- Optimized cleanliness control
- Default waffle pack method
- Alloys available:
 - 80Au/20Sn – 79Au/21Sn
 - 78Au/22Sn – 75Au/25Sn
 - 82Au/18In – 88Au/12Ge



Contact our engineers: askus@indium.com
Learn more: www.indium.com

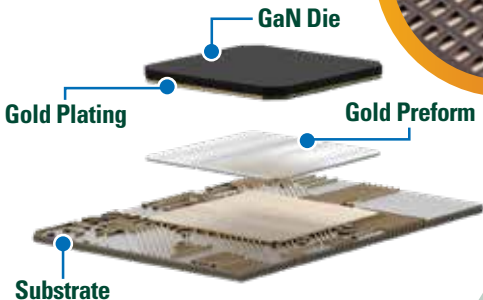
All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

Off-Eutectic Gold Preforms

AuLTRA™ 75

High-performance **precision** materials for critical and **high-reliability** applications

- Au75/Sn25 off-eutectic preforms, also available in Au78/Sn22 & Au79/Sn21
- Improve wetting
- Reduce voiding
- Ensure strongest solder bond



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